

## 500 mA Low-Dropout Linear Regulator

### Features

- Input voltage range: 1.9V to 5V
- Fixed outputs of 1.0V, 1.2V, 1.5V, 1.8V, 2.5V, 2.8V, 3.0V, 3.3V
- Rated output current: 500mA
- Quiescent current: typical 54 $\mu$ A
- Typical 0.1 $\mu$ A shutdown current
- Typical 200mV dropout voltage at 300mA load
- Power supply rejection ratio: typical 72dB ( $I_{OUT}=30mA$ ,  $f_{req}=1kHz$ , 1.8V output)
- Noise: typical 85 $\mu$ Vrms ( $I_{OUT}=30mA$ ,  $BW=10Hz$  to 100kHz, 1.8V output)
- Built-in output short protection: typical 60mA when output short to ground
- Output auto discharge function
- DFN 1mm X1mm X0.37mm-4L package

### General Description

AW3705DXXX is a low dropout voltage regulator featuring low ON resistance, high PSRR, low Noise, good load/line transient response and smooth soft-start.

AW3705DXXX integrates current limit, short circuit protection, thermal shutdown, sufficiently protecting IC from being damaged.

AW3705DXXX is designed to work with a 1 $\mu$ F or more input ceramic capacitor and a 1 $\mu$ F or more output ceramic capacitor. The low power dissipation and good dynamic response make AW3705DXXX very suitable for hand-held communication equipment. Tiny package makes high density mounting of the IC on boards possible.

### Applications

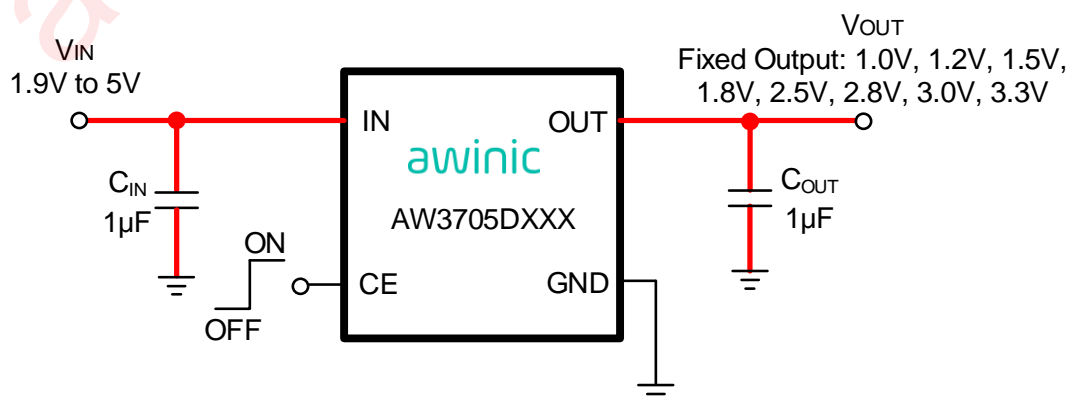
Battery-powered equipment

Smart phone

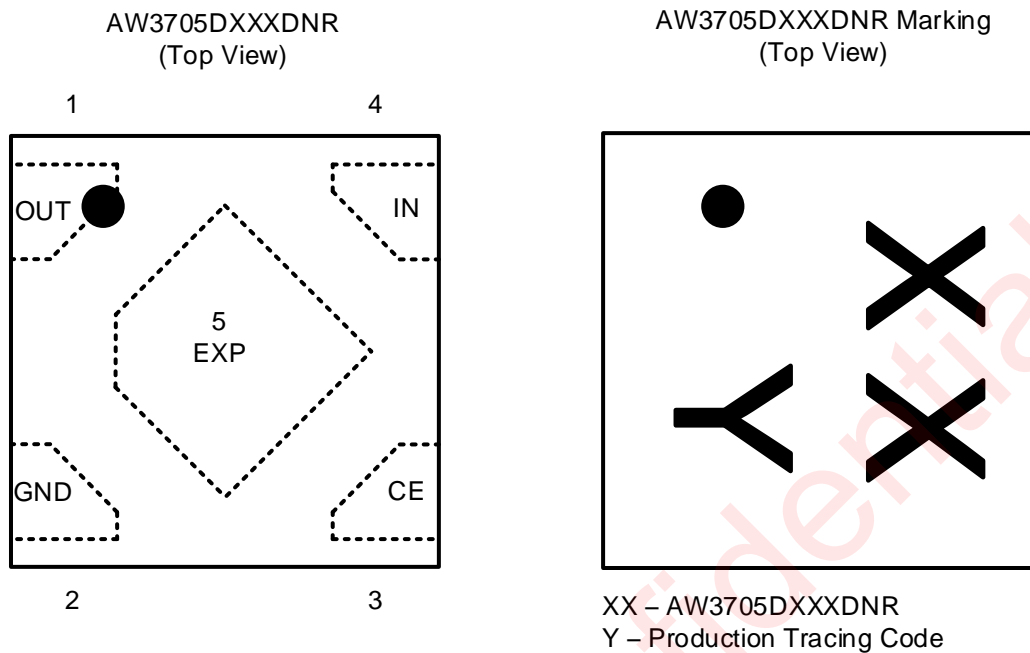
Digital camera

STB

### Typical Application Circuit



## Pin Configuration And Top Mark



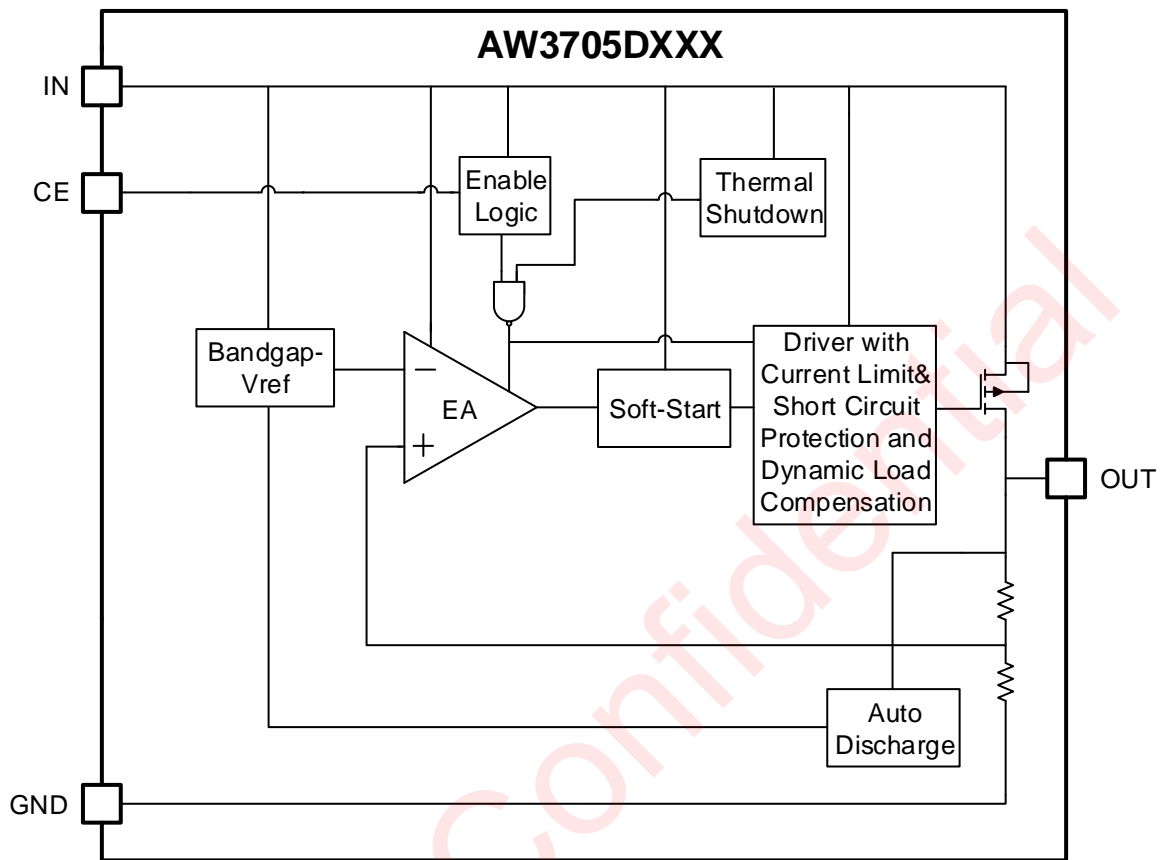
## Pin Definition

No.	NAME	DESCRIPTION
1	OUT	Regulated output voltage pin. Put a 1 $\mu$ F or more ceramic capacitor at the output pin.
2	GND	Ground.
3	CE	Chip enable pin. Built-in pull-down resistor. (High Active)
4	IN	Input supply pin. Add a 1 $\mu$ F or more bypass capacitor at the power supply.
5	EXP	Expose pad should be tied to ground plane for better power dissipation.

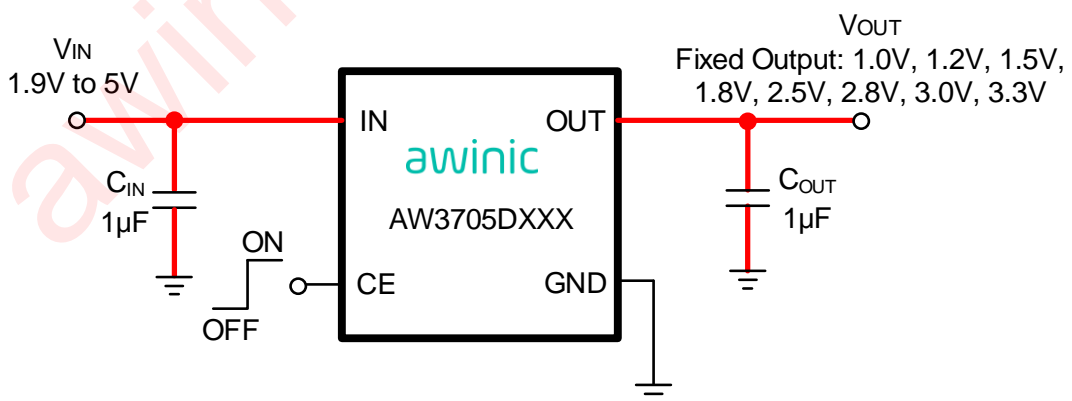
## Device Comparison Table

Part Number	V <sub>OUT(SET)</sub>	Rated Current	CE Active	Auto Discharge
AW3705D100DNR	1.0V	500mA	High	YES
AW3705D120DNR	1.2V	500mA	High	YES
AW3705D150DNR	1.5V	500mA	High	YES
AW3705D180DNR	1.8V	500mA	High	YES
AW3705D250DNR	2.5V	500mA	High	YES
AW3705D280DNR	2.8V	500mA	High	YES
AW3705D300DNR	3.0V	500mA	High	YES
AW3705D330DNR	3.3V	500mA	High	YES

## Functional Block Diagram



## Typical Application Circuits



AW3705DXXX Application circuit

### Notice for typical application circuits:

Capacitance of  $C_{IN}$  and  $C_{OUT}$  should be  $1\mu\text{F}$  or more.

## Ordering Information

Part Number	Temperature	Package	Marking	Moisture Sensitivity Level	Environmental Information	Delivery Form
AW3705D100 DNR	-40°C~85°C	DFN 1mmX1mm -4L	AC	MSL1	ROHS+HF	3000 units/Tape and Reel
AW3705D120 DNR	-40°C~85°C	DFN 1mmX1mm -4L	AG	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW3705D150 DNR	-40°C~85°C	DFN 1mmX1mm -4L	AM	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW3705D180 DNR	-40°C~85°C	DFN 1mmX1mm -4L	AS	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW3705D250 DNR	-40°C~85°C	DFN 1mmX1mm -4L	BG	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW3705D280 DNR	-40°C~85°C	DFN 1mmX1mm -4L	BM	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW3705D300 DNR	-40°C~85°C	DFN 1mmX1mm -4L	BQ	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW3705D330 DNR	-40°C~85°C	DFN 1mmX1mm -4L	BW	MSL1	ROHS+HF	3000 units/ Tape and Reel

**Absolute Maximum Ratings**<sup>(NOTE1)</sup>

PARAMETERS	RANGE
Input voltage range $V_{BUS}$	-0.3V to 6V
Enable control voltage range	-0.3V to 6V
Output voltage range	-0.3V to 6V
Junction-to-ambient thermal resistance $\theta_{JA}$ <sup>(NOTE2)</sup>	250°C/W
Operating free-air temperature range	-40°C to 85°C
Maximum operating junction temperature $T_{JMAX}$	150°C
Storage temperature $T_{STG}$	-65°C to 150°C
Lead temperature (soldering 10 seconds)	260°C
ESD	
HBM (Human body model) <sup>(NOTE3)</sup>	±2kV
CDM(Charged device model) <sup>(NOTE4)</sup>	±1.5kV
MM(Machine Model) <sup>(NOTE5)</sup>	±200V
Latch-Up	
Latch-Up <sup>(NOTE6)</sup>	+IT: 200mA -IT: -200mA

*NOTE1: Conditions out of those ranges listed in "absolute maximum ratings" may cause permanent damages to the device. In spite of the limits above, functional operation conditions of the device should within the ranges listed in "recommended operating conditions". Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.*

*NOTE2: Thermal resistance from junction to ambient is highly dependent on PCB layout.*

*NOTE3: All pins. Test Condition: ESDA/JEDEC JS-001-2017.*

*NOTE4: All pins. Test Condition: ESDA/JEDEC JS-002-2014.*

*NOTE5: All pins. Test Condition: JESD22 A115C.*

*NOTE6: Test Condition: JESD78E.*

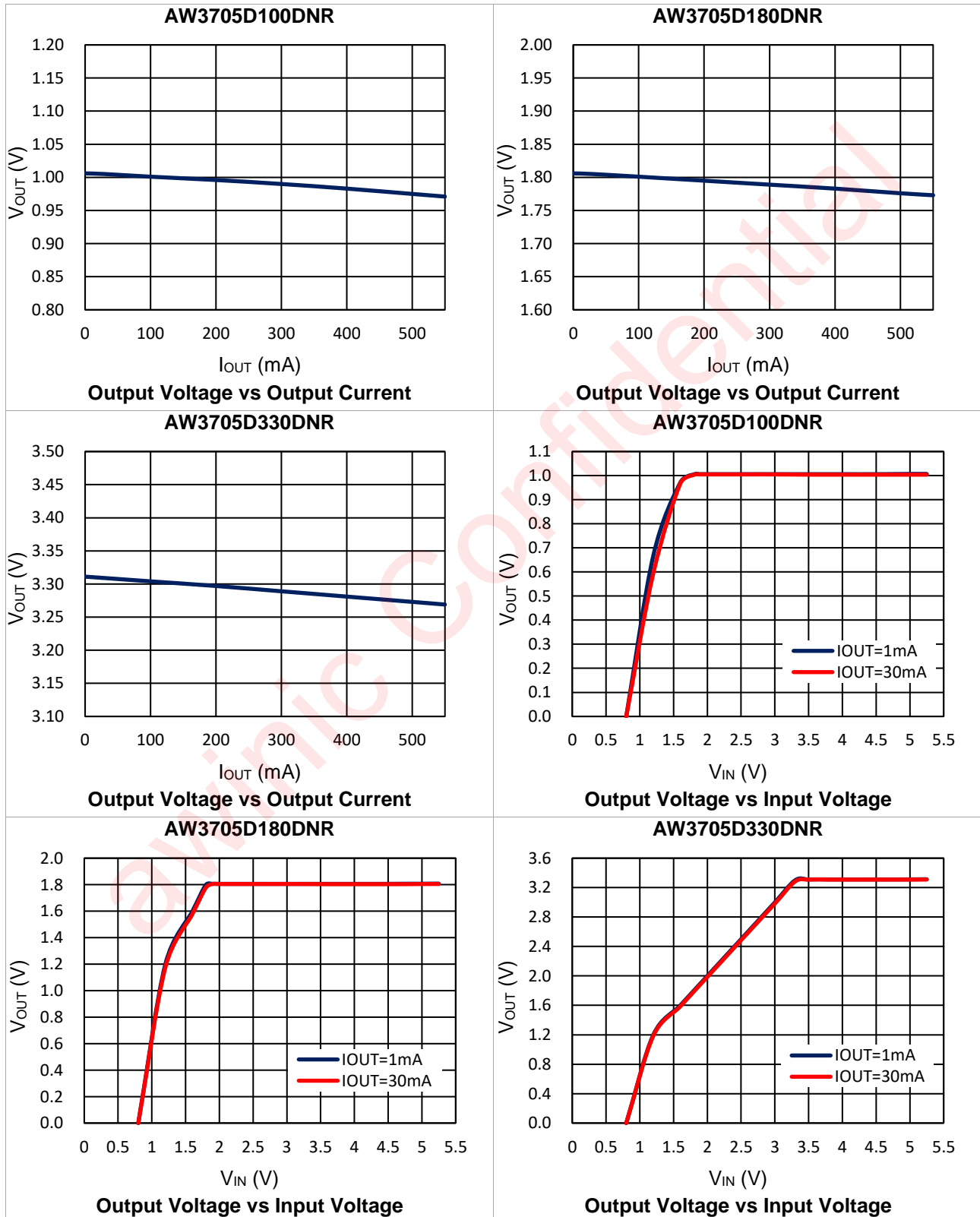
## Electrical Characteristics

$V_{IN}=V_{OUT(SET)}+1V$ ,  $V_{CE}>1.2V$ ,  $I_{OUT}=1mA$ ,  $C_{IN}=C_{OUT}=1\mu F$ ,  $T_A=25^{\circ}C$  (unless otherwise noted)

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
$V_{IN}$	Input Voltage Range		1.9		5	V
$V_{OUT\_ACC}$	Output Voltage Accuracy		-3		3	%
$LOAD_{Reg}$	Load Regulation	$1mA \leq I_{OUT} \leq 500mA$		30	68	mV
$LINE_{Reg}$	Line Regulation	$V_{OUT(SET)}+0.5V \leq V_{IN} \leq 5V$		0.06	0.15	%/V
$V_{dropout}$	Dropout Voltage	$I_{OUT}=300mA$ (for AW3705D180DNR)		200		mV
$I_{SD}$	Shutdown Current	$V_{CE}<0.4V$		0.1	1	$\mu A$
$I_Q$	Quiescent Current	$I_{OUT}=0mA$		54	80	$\mu A$
$V_{CEH}$	CE Input Voltage "H"	$-40^{\circ}C \leq T_A \leq 85^{\circ}C$	1.2			V
$V_{CEL}$	CE Input Voltage "L"	$-40^{\circ}C \leq T_A \leq 85^{\circ}C$			0.4	V
PSRR	Power Supply Ripple Rejection	$I_{OUT}=30mA$ , $f=1kHz$ (for AW3705D180DNR)		72		dB
$V_N$	Output Voltage Noise	$I_{OUT}=30mA$ , $BW=10Hz$ to $100kHz$		45* $V_{OUT(SET)}$		$\mu V_{rms}$
$I_{CL}$	Output Current Limit	$V_{OUT}=90%*V_{OUT(SET)}$	550	850		mA
$I_{SC}$	Short Current Limit	$V_{OUT}<10%*V_{OUT(SET)}$		60		mA
VTC	Output Voltage Temperature Coefficient	$-40^{\circ}C \leq T_A \leq 85^{\circ}C$		$\pm 80$		ppm/ $^{\circ}C$
$R_{DISC}$	Auto Discharge Resistance	$V_{CE}<0.4V$ , $I_{OUT}=0mA$		160		$\Omega$
$T_{SDH}$	Thermal Shutdown Threshold	Temperature Rising		150		$^{\circ}C$
$T_{SDL}$	Thermal Shutdown Reset Threshold	Temperature Falling		130		$^{\circ}C$

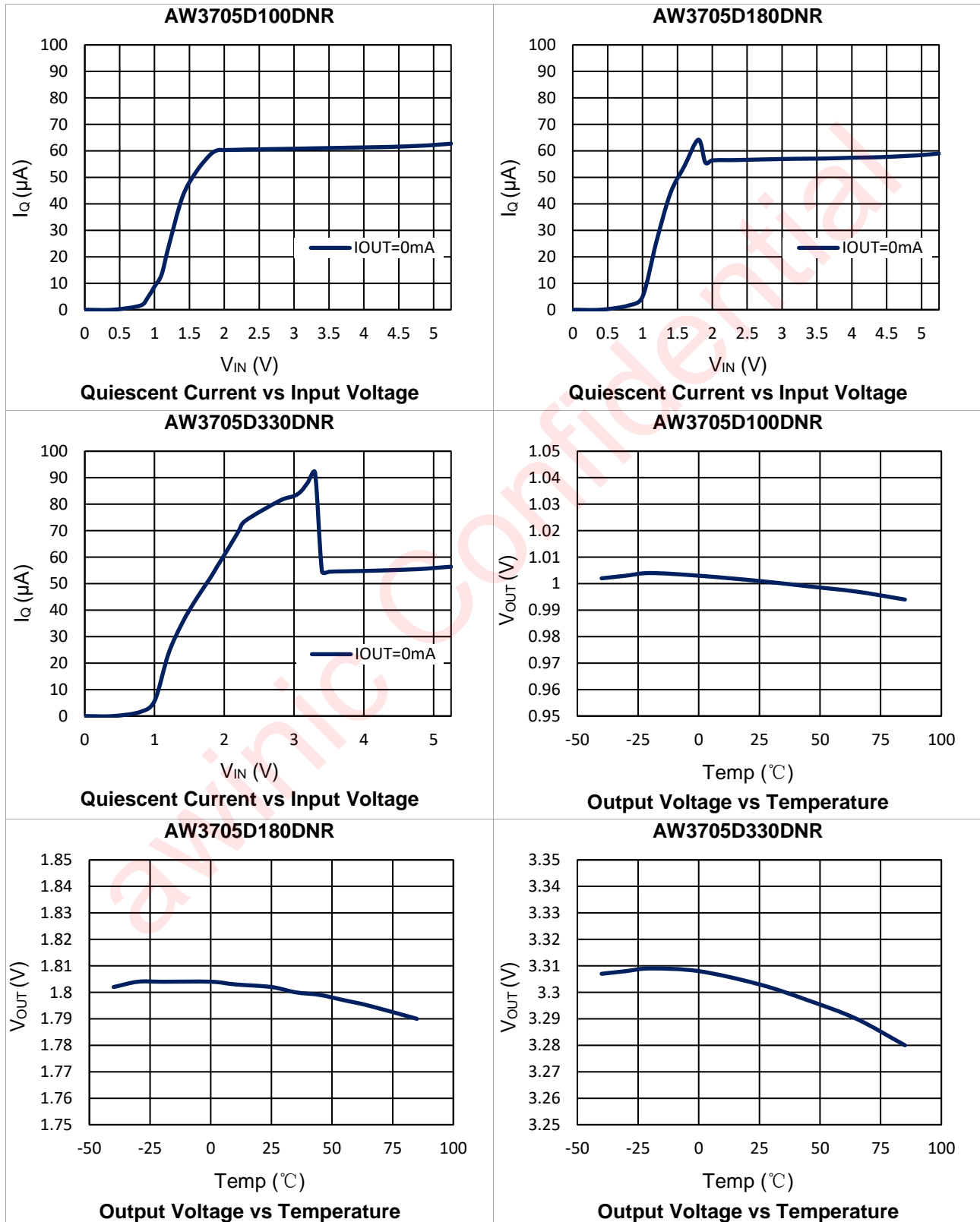
## Typical Characteristics

$V_{IN} = V_{OUT(SET)} + 1V$ ,  $V_{CE} > 1.2V$ ,  $I_{OUT} = 1mA$ ,  $C_{IN} = C_{OUT} = 1\mu F$ ,  $T_A = 25^\circ C$ , In Typical Application Circuit, unless other noted.



## Typical Characteristics (Continued)

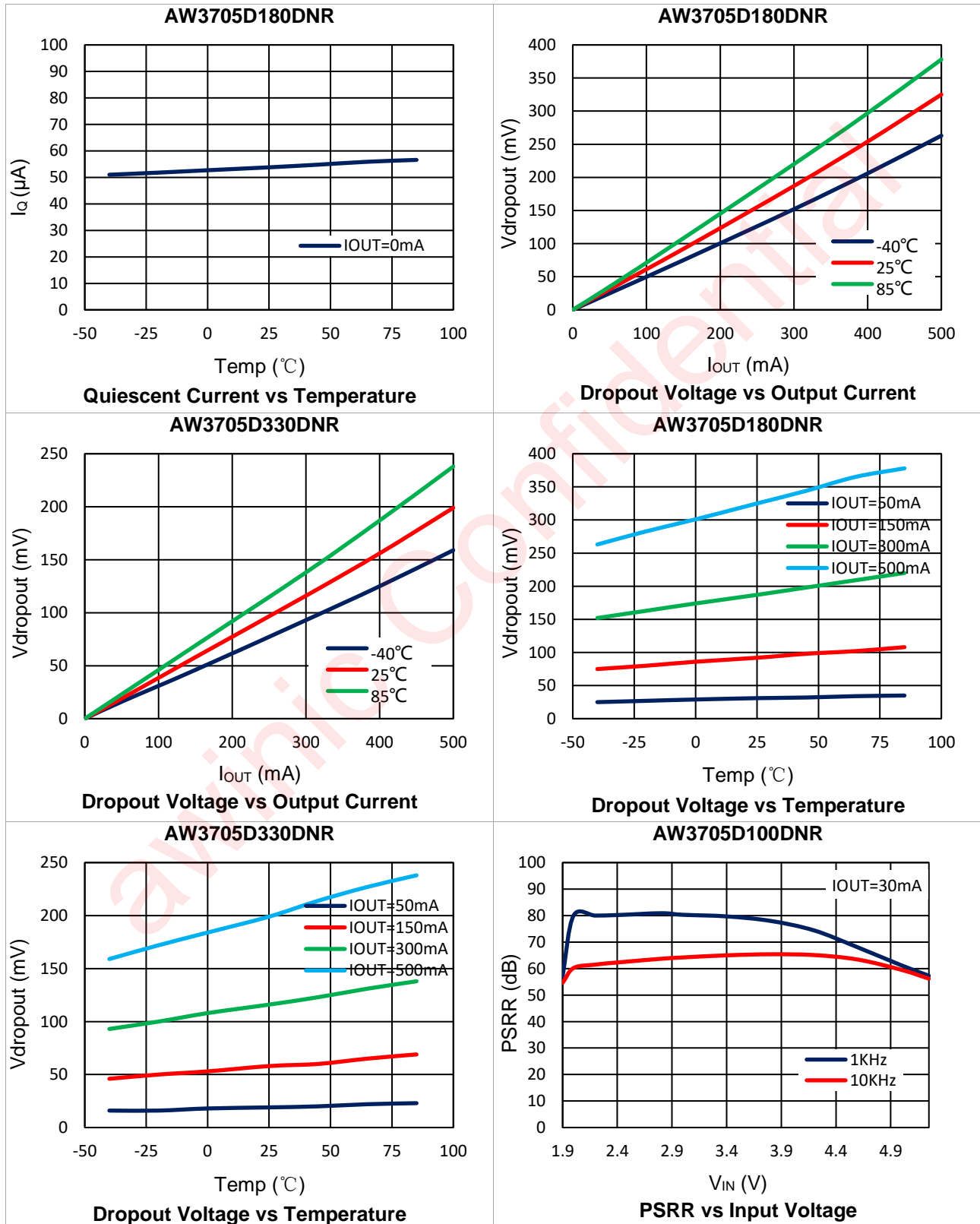
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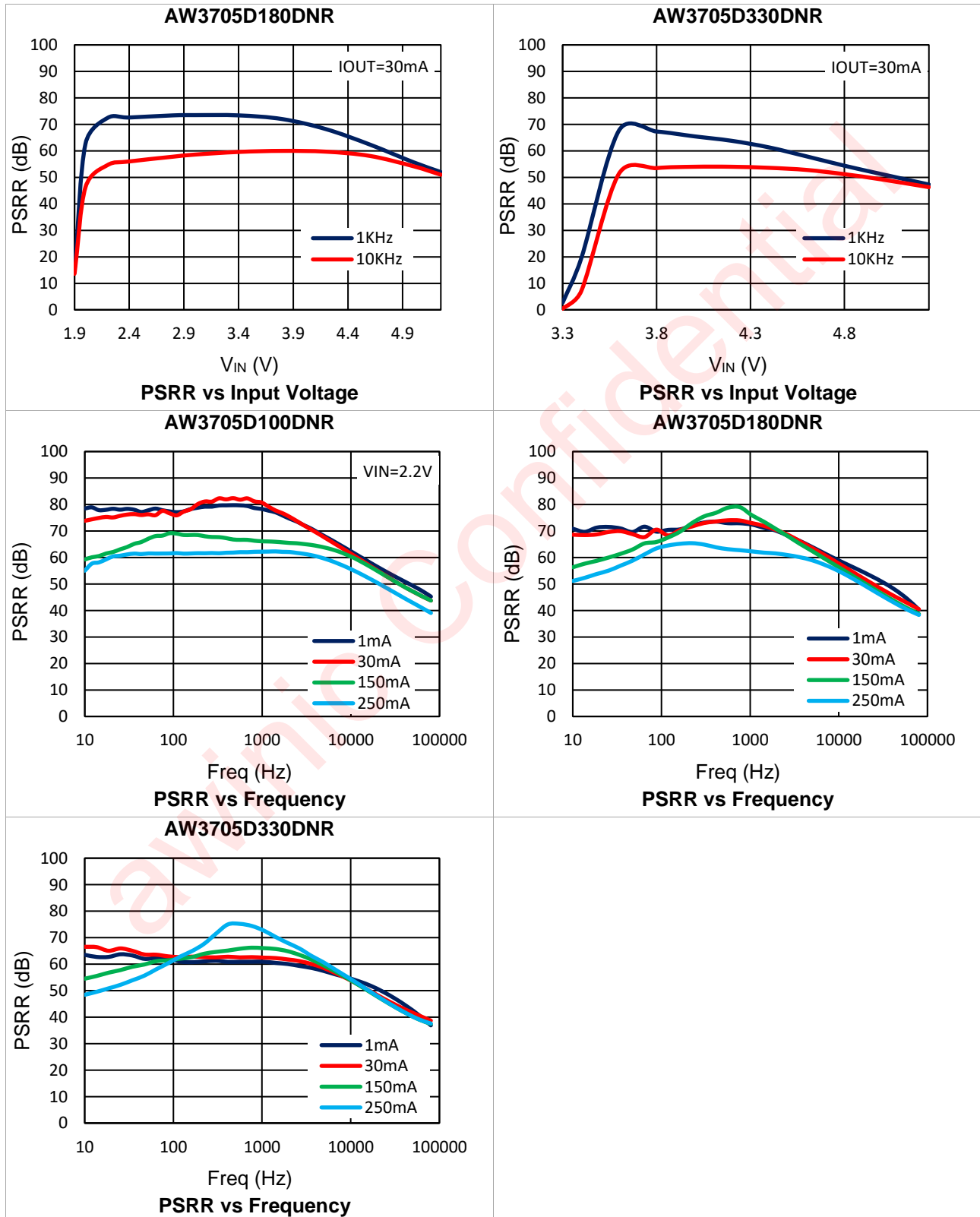
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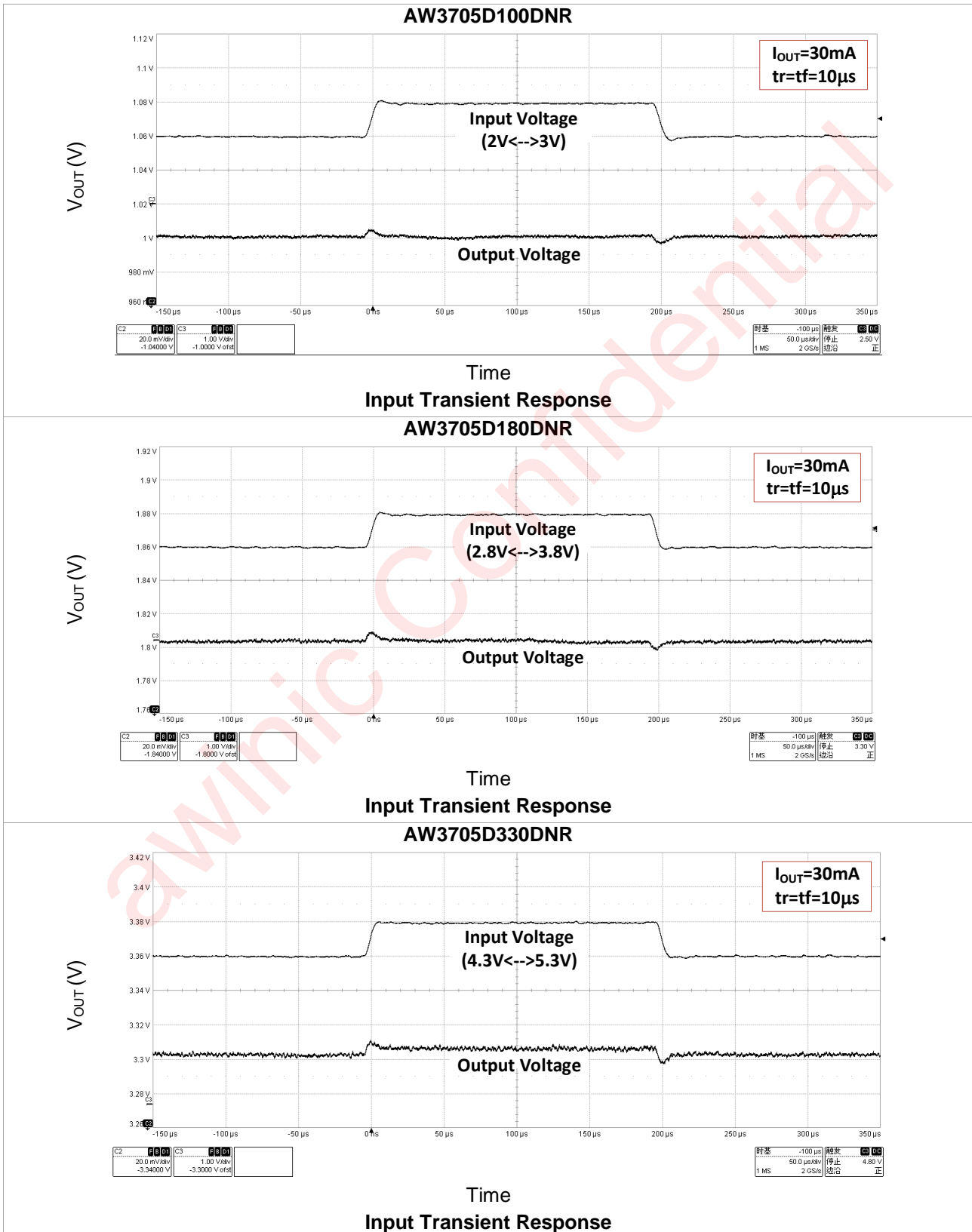
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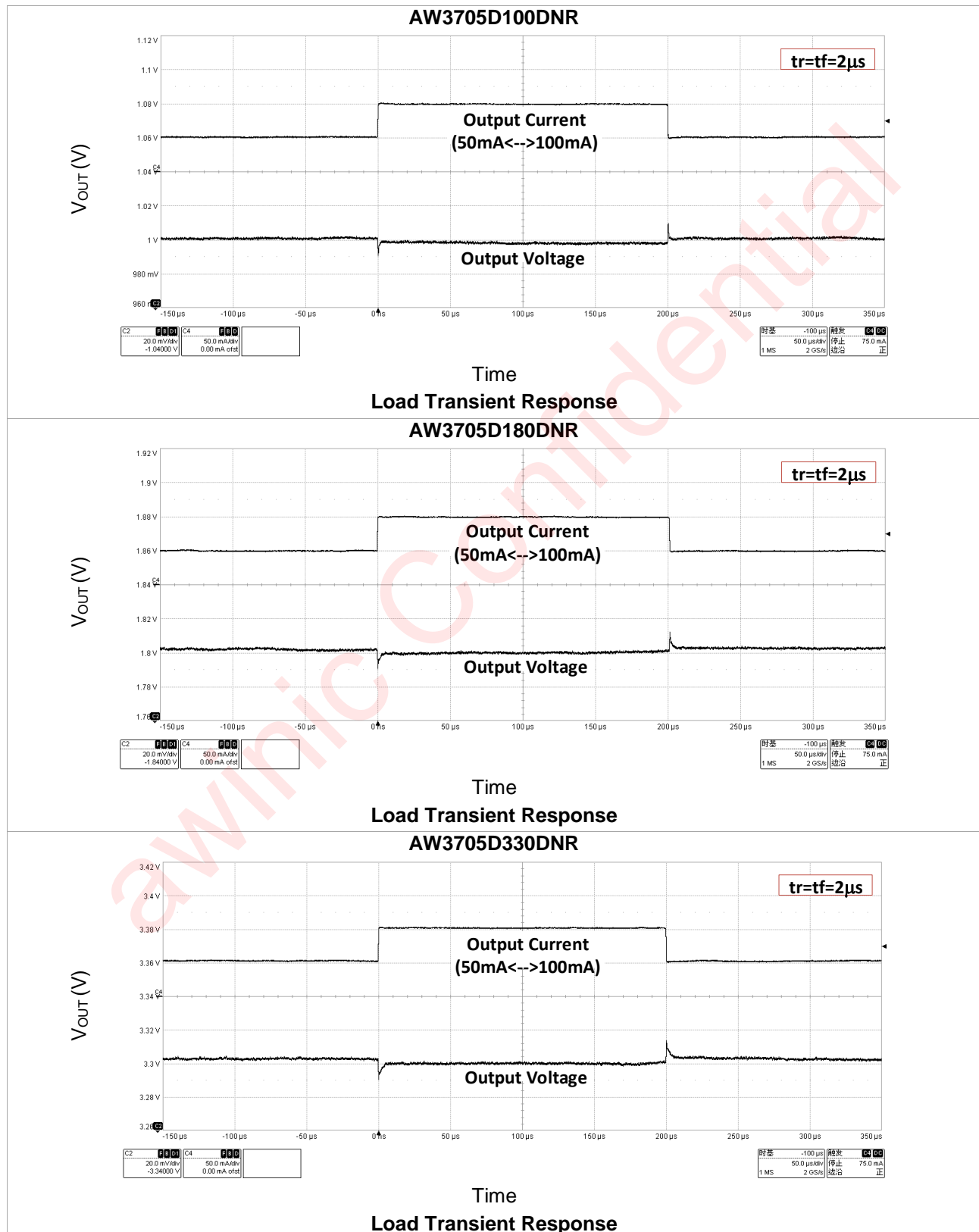
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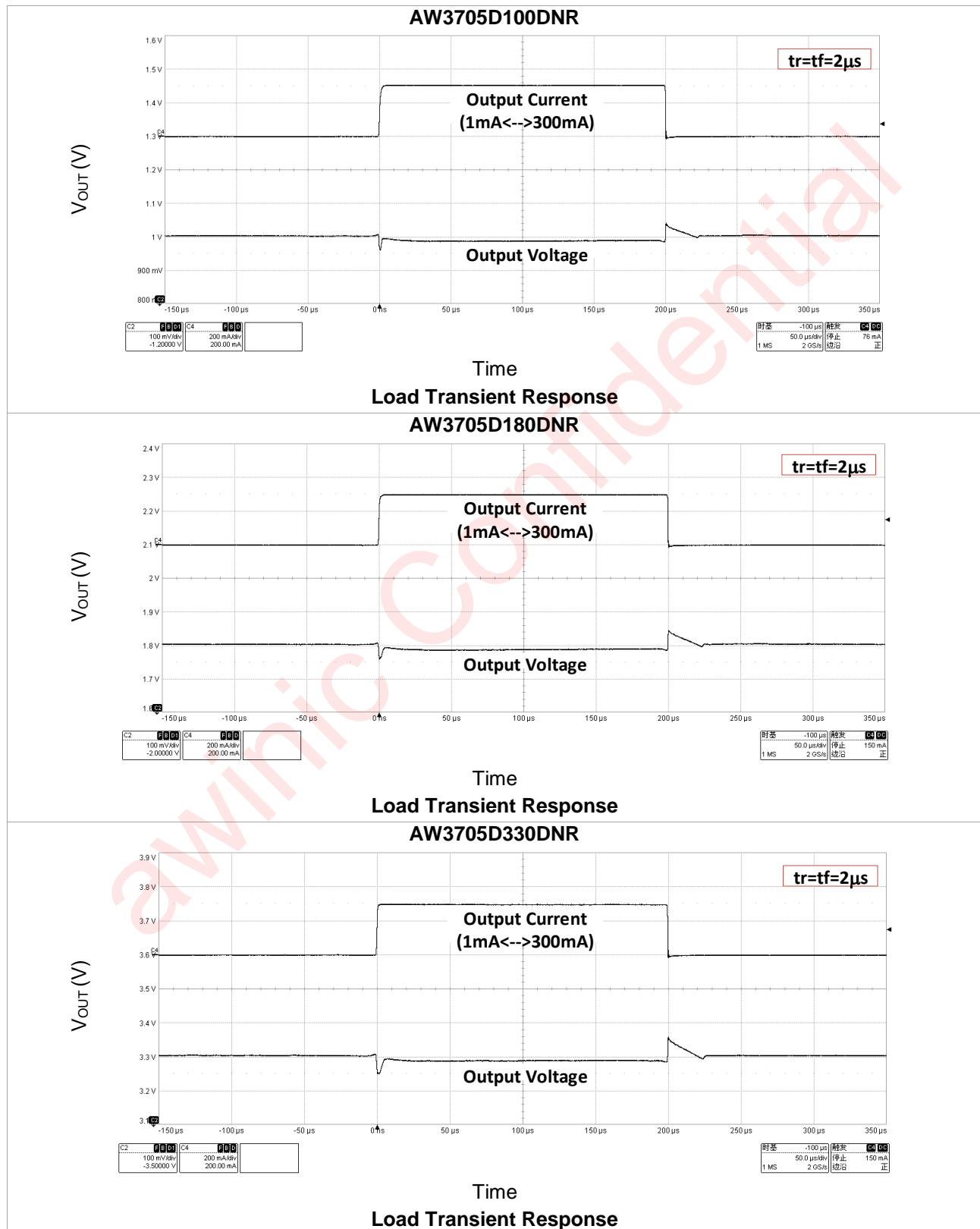
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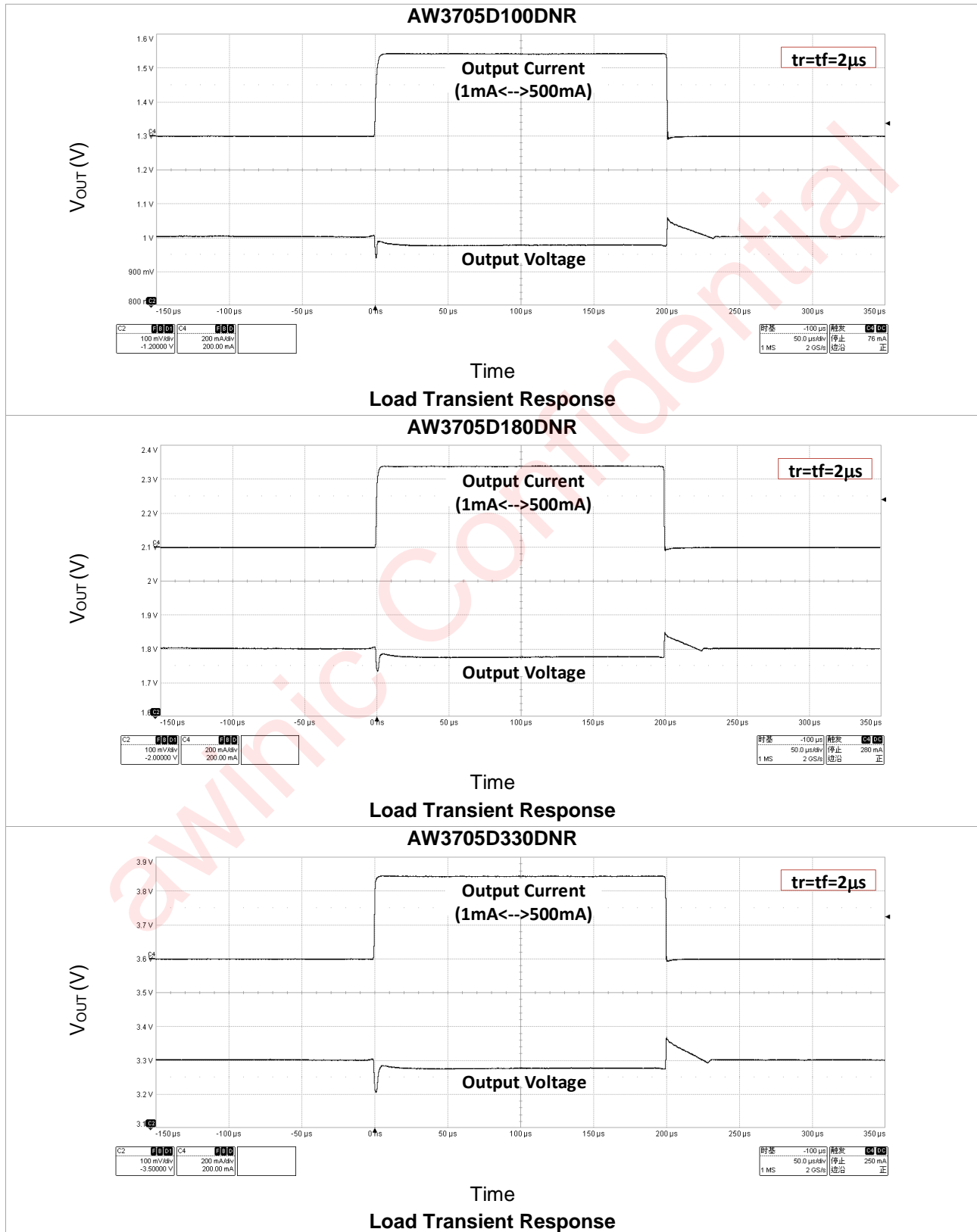
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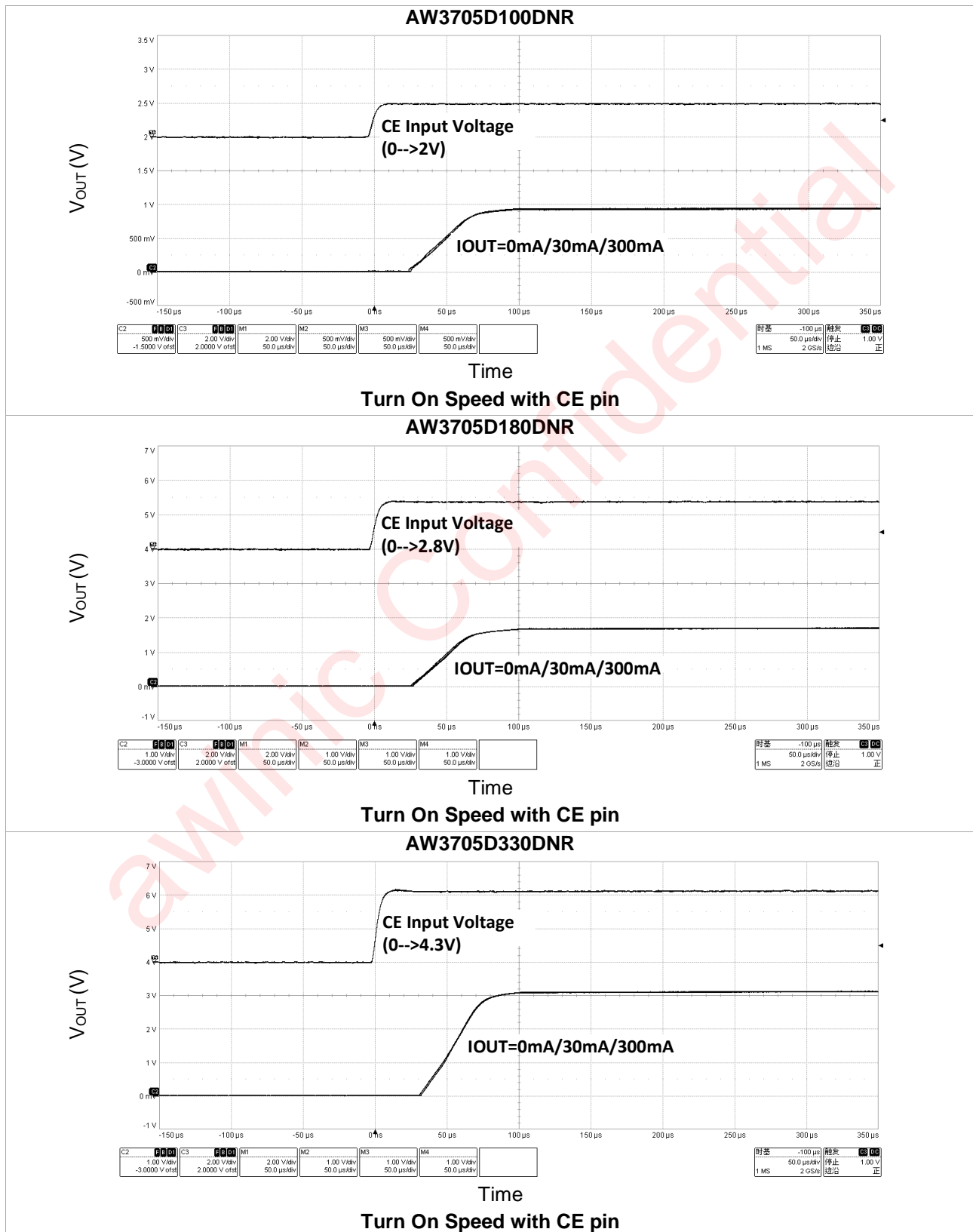
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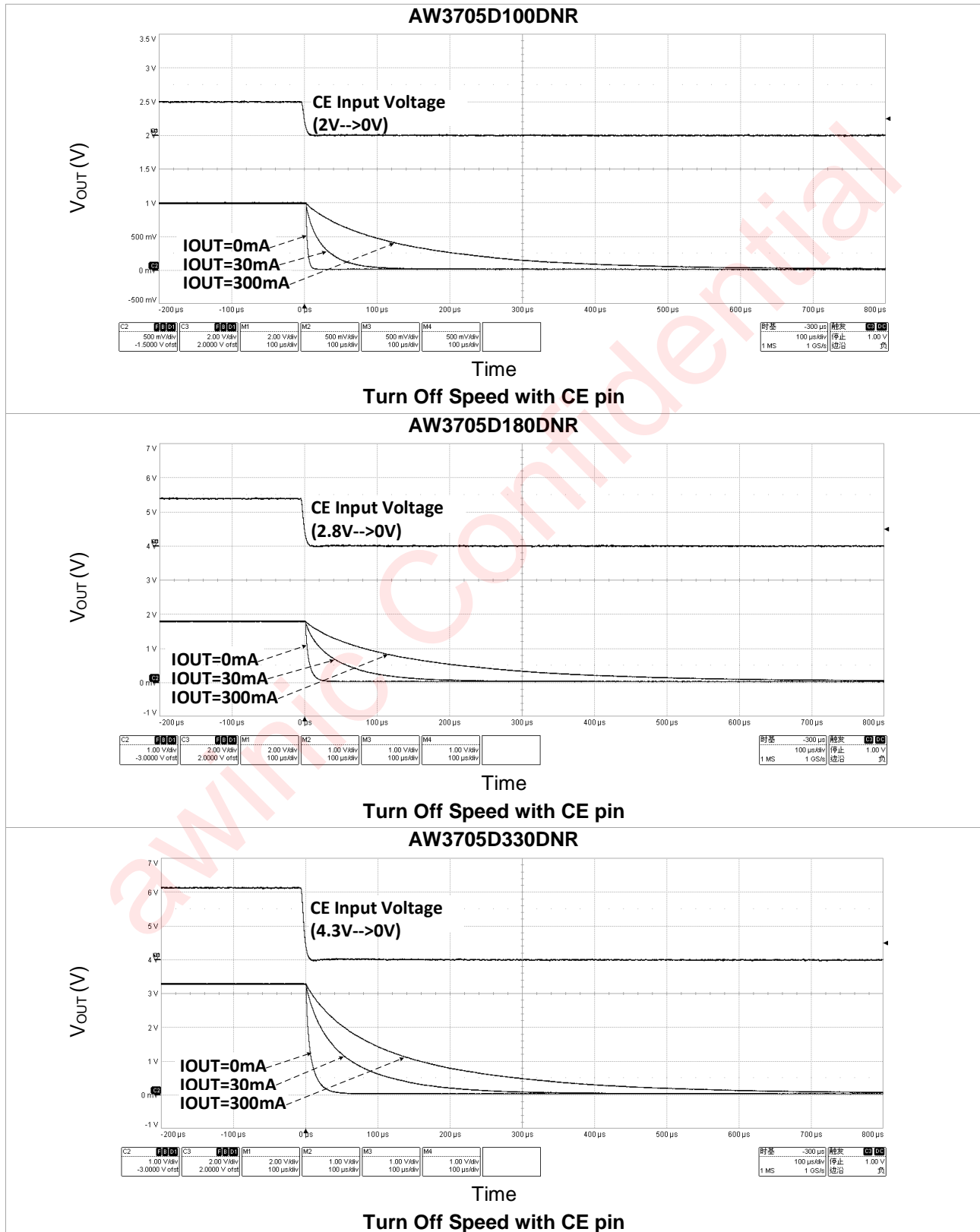
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## Detailed Functional Description

AW3705DXXX is a low dropout voltage regulator. After powered on, with CE pin assertion, feedback voltage signal from the integrated resistor network and a voltage related to the voltage reference are transmit to positive input terminal and negative input terminal of an error amplifier (EA) respectively. The output signal of EA is used to control the open-state of power MOSFET. After soft-start, feedback voltage signal compares with the established reference voltage, making output voltage stable and accurate. AW3705DXXX integrates function of adaptive dynamic bias compensation. It means, as load current increases, bias currents for EA also increase, making LDO obtain excellent dynamic response performance.

### Enable Operation

AW3705DXXX uses CE pin to realize enable operation. Applying proper value of voltage to CE pin can make IC enable/disable.

If the voltage of CE pin is less than 0.4V, AW3705DXXX is guaranteed to be disabled. In this state, function modules of IC and power MOSFET are turned off. And the auto discharge function is open making output discharge through a 160Ω resistor to Ground. In disable state, AW3705DXXX only consumes a typical 10nA current.

If the voltage of CE pin is more than 1.2V, AW3705DXXX is guaranteed to be enabled. In this state, the auto discharge MOSFET is closed, and AW3705DXXX regulates output voltage to the designed value of voltage.

A 4MΩ resistor to Ground is built-in at CE pin, making sure that the IC is disabled when CE pin floats. If Enable function is not required, CE pin should be connected directly to IN pin.

### Output Current Limit

AW3705DXXX integrates output current limit function, protecting IC from excessive current.

When the load is excessively heavy, AW3705DXXX limits the current flowing through the IC to a typical 800mA current. This value is specially designed, so that IC is protected properly and the output capability of 500mA is not influenced either.

Meanwhile, AW3705DXXX integrates fold-back current limit function, lowering the system dissipation when output overload or short to Ground.

### Thermal Shutdown

AW3705DXXX integrates thermal shutdown function, protect IC from excessively high temperature.

When the chip temperature exceeds 150°C, AW3705DXXX detects it as an over-temperature event, triggering thermal shutdown, which will turn off the main function module, including power MOSFET. This inhibits increase of chip's temperature. IC would keep the protection-state on until the chip's temperature falls below to 130°C. At this moment, the over-temperature protection-state is released, IC resumes to work again. The hysteresis avoids IC's turning off and on frequently around the the Thermal Shutdown threshold.

### Auto Discharge

AW3705DXXX makes output voltage decrease quickly when in disable state or thermal shutdown state, benefit from integrating auto discharge function.

## Application Information

### Capacitors Selection

#### **IN pin: Input Capacitor $C_{IN}$**

AW3705DXXX advises to use a 1 $\mu$ F or more X5R or X7R ceramic capacitor at IN pin as shown in Typical Application Circuit.

#### **OUT pin: Output Capacitor $C_{OUT}$**

AW3705DXXX advises to use a 1 $\mu$ F or more X5R or X7R ceramic capacitor at OUT pin as shown in Typical Application Circuit.

*NOTE: For the application with fast load transient, capacitance of the input capacitor is recommended to be equal or larger to the sum of the capacitance at the output node for the best load transient performance.*

### Recommended Components List

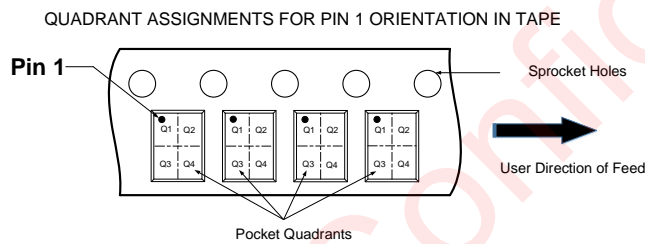
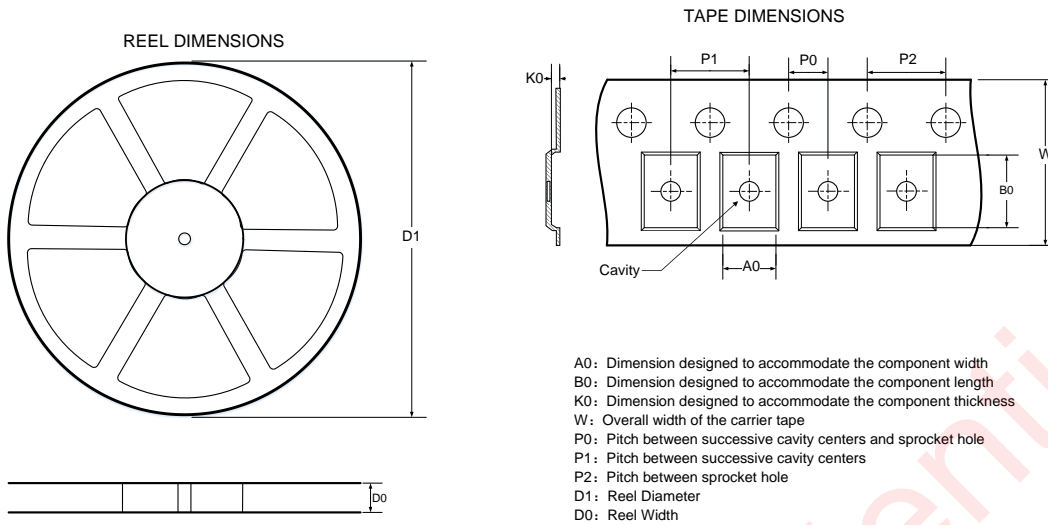
Component	PART No.	DESCRIPTION	MFR	TYP.	UNIT
$C_{IN}$	GRM155R61A105KE15	10V, X5R, 0402	MURATA	1	$\mu$ F
$C_{OUT}$	GRM155R61A105KE15	10V, X5R, 0402	MURATA	1	$\mu$ F

### PCB Layout Consideration

To obtain the optimal performance, guidelines below for PCB layout of AW3705DXXX should be obeyed:

1. All peripheral components should be placed as close to the chip as possible.  $C_{IN}$  and  $C_{OUT}$  should be close to IN and OUT pins respectively. Avoid connecting device and chip pins with two different layers of copper, use the same layer of copper instead.
2. IN and OUT pin are the large current input and output of the chip, make IN, OUT, and meanwhile GND lines sufficient.
3. The connection lines between the planes of  $C_{IN}$  or  $C_{OUT}$  and respective chip pin should be as short and wide as possible, to reduce noise and EMI interference.
4. The exposed plane of chip and GND pins must be connected to the large-area ground layer of PCB directly, meanwhile place sufficient vias below the exposed plane. Thus we can decrease the thermal resistor on the board to optimize heat-diffusion performance.

## Tape And Reel Information

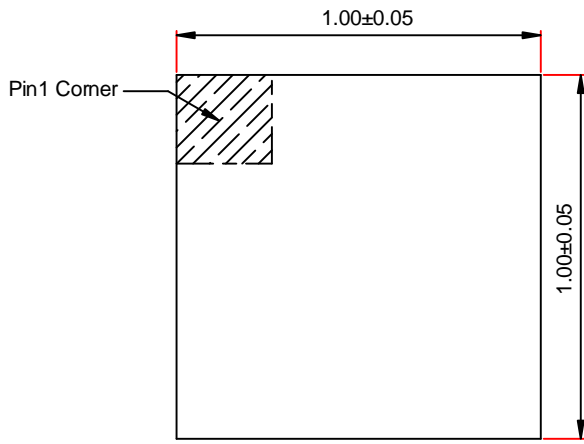


DIMENSIONS AND PIN1 ORIENTATION

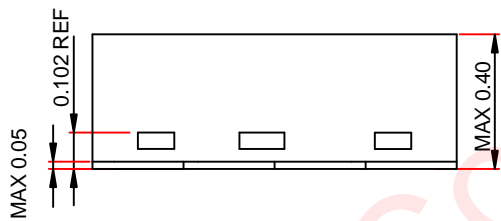
D1 (mm)	D0 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
178	8.4	1.14	1.17	0.56	2	4	4	8	Q1

All dimensions are nominal

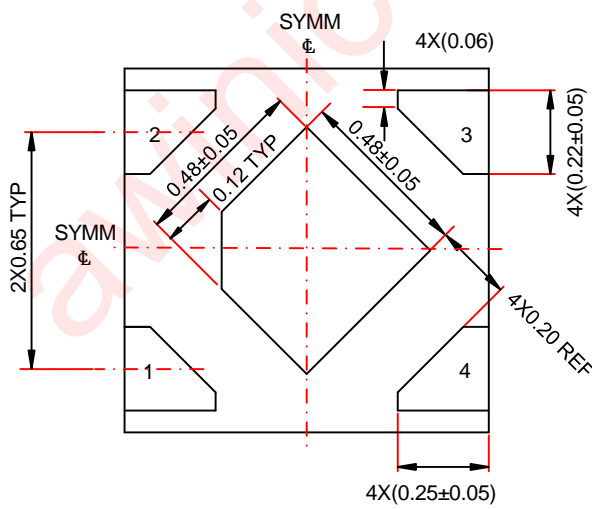
Package Description



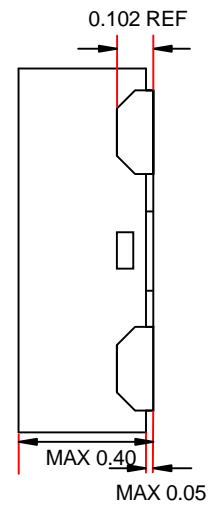
Top View



Side View



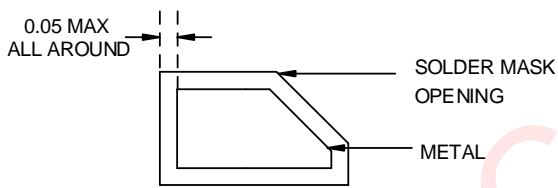
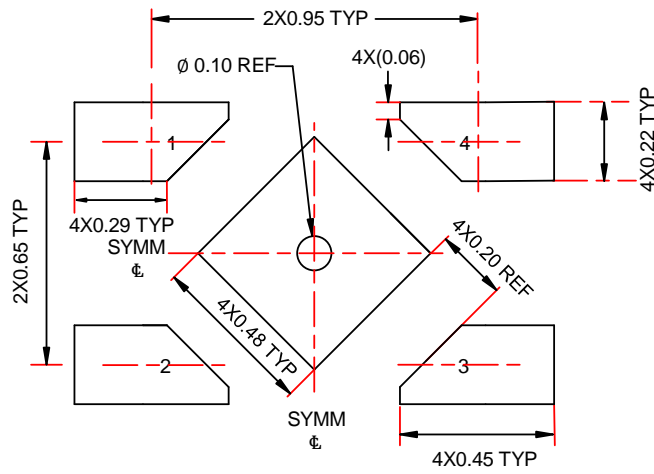
Bottom View



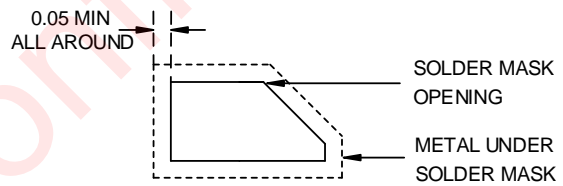
Side View

Unit:mm

Land Pattern Data



NON SOLDER MASK DEFINED



SOLDER MASK DEFINED

UNIT : mm

## Revision History

Version	Date	Change Record
V1.0	Sept 2018	Officially released

awinic Confidential

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